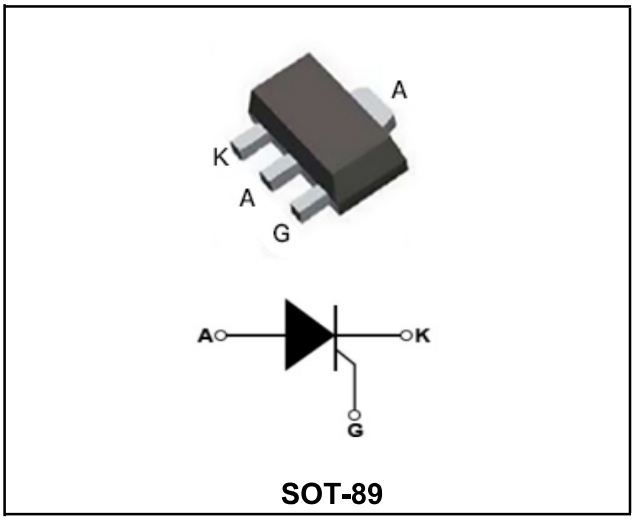
Silicon Controlled Rectifiers



SOT-89

■ Features

- Blocking voltage to 600 V
- Average on-state current to 0.5 A
- General purpose switching

■ Absolute Maximum Ratings Ta = 25℃

Parameter	Symbol	Rating	Unit
Repetitive peak off-state voltages	V_{DRM},V_{RRM}	600	V
Average on-state current	$I_{T(AV)}$	0.5	A
RMS on-state current	$I_{T(RMS)}$	0.8	A
Non-repetitive peak on-state current	I_{TSM}	8	A

■ Electrical Characteristics Ta = 25℃

Parameter	Symbol	Test conditions		Min	Typ	Max	Unit
Repetitive peak off-state voltages	V_{DRM}			600			V
Average on-state current	$I_{T(AV)}$	Half sine wave;Tlead≤ 83 ℃				0.5	A
RMS on-state current	$I_{T(RMS)}$	All conduction angles				0.8	A
Non-repetitive peak on-state current	I_{TSM}	full sine wave;	t = 10 ms			8	A
		Tj = 25℃ prior to surge	t = 8.3 ms			9	A
I^2t for fusing	I^2t	t = 10 ms				0.32	A^2S
Repetitive rate of rise of on-state current after triggering	dI_T/dt	I_{TM} = 2 A; I_G = 10m A; dI_G/dt = 100m A/μs				50	A/μs
Peak gate current	I_{GM}					1	A
Peak gate voltage	V_{GM}					5	V
Peak gate power	P_{GM}					2	W
Average gate power	$P_{G(AV)}$	over any 20 ms period				0.1	W
Thermal resistance junction to ambient	$R_{\theta JA}$	PCB mounted,lead length=4mm			150		K/W
Storage temperature	T_{stg}			-40		150	℃
Operating junction temperature	T_j					125	℃

■ Electrical Characteristics Ta = 25℃

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Gate trigger current	I_{GT}	V_D = 12 V; I_T = 10m A,gate open circuit		50	200	μA
Latching current	I_L	V_D = 12 V; I_{GT} = 0.5mA R_{GK}=1KΩ		2	6	mA
Holding current	I_H	V_D = 12 V; I_{GT} = 0.5mA R_{GK}=1KΩ		2	5	
On-state voltage	V_T	I_T = 1 A		1.2	1.35	V
Gate trigger voltage	V_{GT}	V_D = 12 V; I_T = 10mA,gate open circuit		0.5	0.8	V
		V_D = $V_{DRM(max)}$; I_T = 10mA; Tj = 125 ℃	0.2	0.3		V
Off-state leakage current	I_D,I_R	V_D = $V_{DRM(max)}$;V_R=$V_{RRM(max)}$ Tj = 125 ℃ R_{GK}=1KΩ		0.05	0.1	mA
Critical rate of rise of off-state voltage	dV_D/dt	V_{DM} =67% $V_{DRM(max)}$; Tj = 125℃; exponential R_{GK}=1KΩ		25		V/μS
Gate controlled turn-on time	t_{gt}	I_{TM}=2A;V_D=$V_{DRM(max)}$; I_G=10mA dI_G/dt = 0.1 A/μs		2		μS
Circuit commutated turn-off time	t_q	I_{TM} = 1.6 A; V_D = 67%$V_{DRM(max)}$; Tj=125℃;V_R=35V;R_{GK}=1kΩ dI_{TM}/dt = 30 A/μs;V_D/dt = 2V/μs		100		μS

■ Typical Characteristics

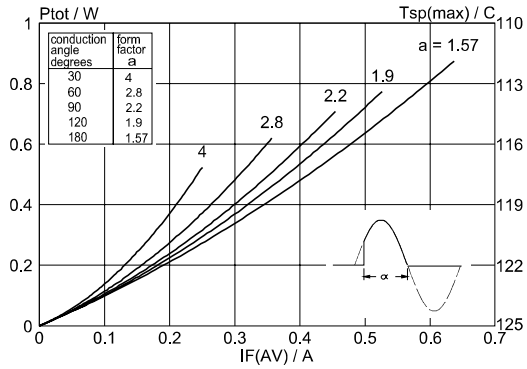


Fig.1. Maximum on-state dissipation, P_{tot}, versus average on-state current, $I_{T(AV)}$, where a = form factor = $I_{T(RMS)}/I_{T(AV)}$.

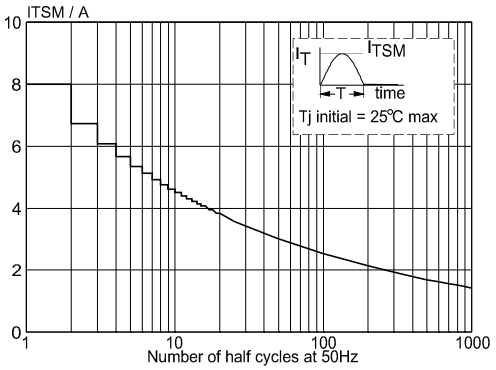


Fig.4. Maximum permissible non-repetitive peak on-state current I_{TSM}, versus number of cycles, for sinusoidal currents, f = 50 Hz.

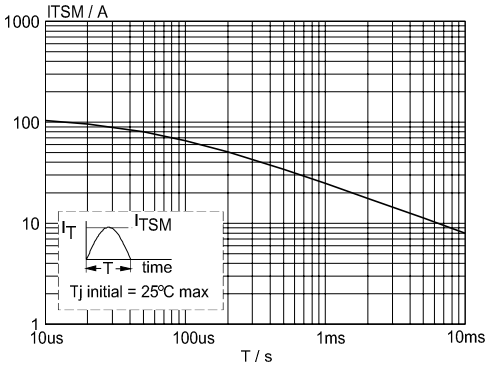


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM}, versus pulse width t_p, for sinusoidal currents, $t_p \leq 10ms$.

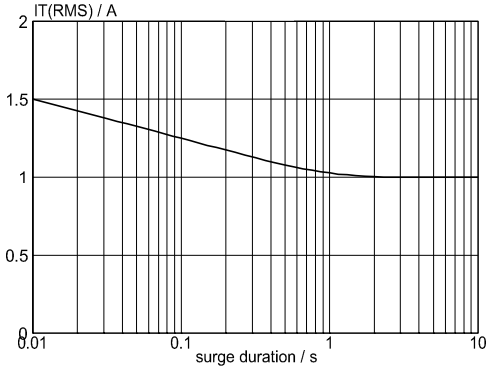


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{sp} \leq 112^{\circ}C$.

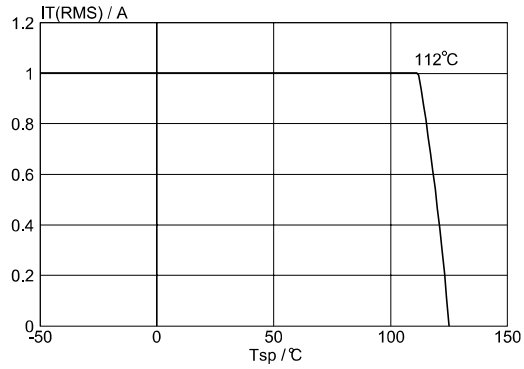


Fig.3. Maximum permissible rms current $I_{T(RMS)}$, versus solder point temperature T_{sp}.

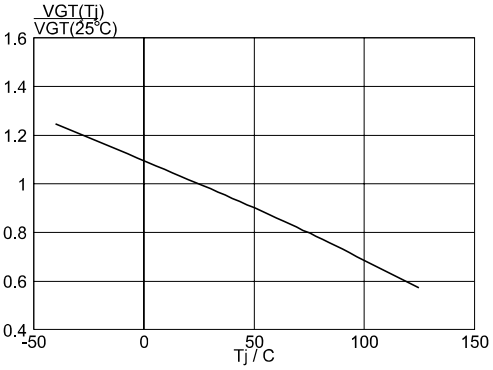


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/ V_{GT}(25^{\circ}C)$, versus junction temperature T_j.

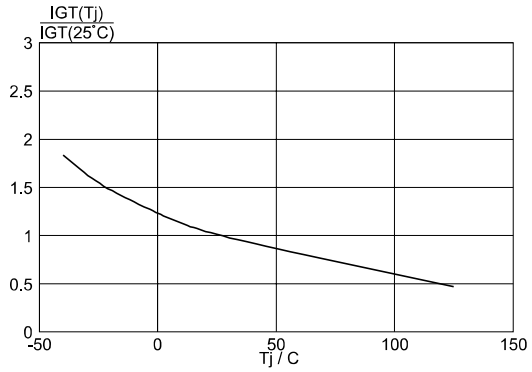


Fig.7. Normalised gate trigger current $I_{GT}(T_j)/ I_{GT}(25^{\circ}C)$, versus junction temperature T_j.

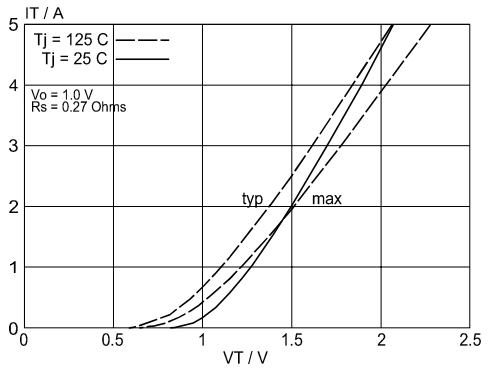


Fig.10. Typical and maximum on-state characteristic.

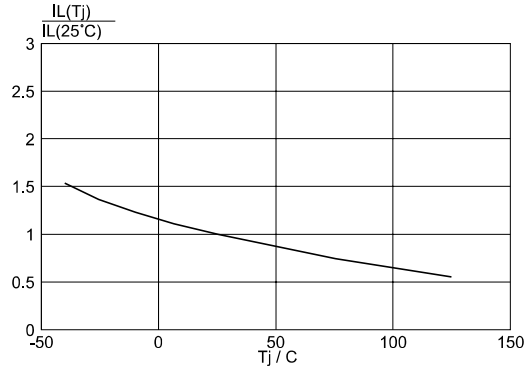


Fig.8. Normalised latching current $I_L(T_j)/ I_L(25^{\circ}C)$, versus junction temperature T_j, R_{GK} = 1 kΩ.

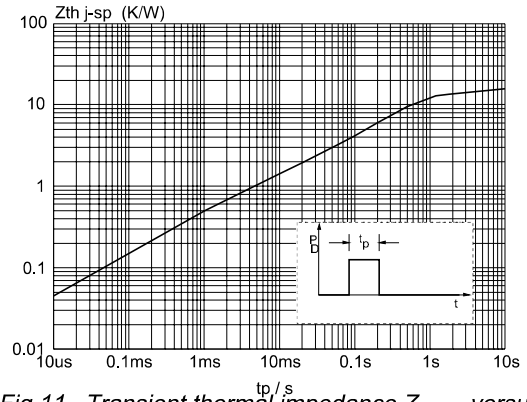


Fig.11. Transient thermal impedance $Z_{th\ j\text{-}sp}$, versus pulse width t_p.

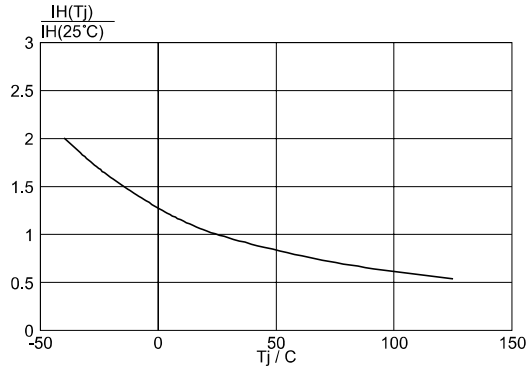


Fig.9. Normalised holding current $I_H(T_j)/ I_H(25^{\circ}C)$, versus junction temperature T_j, R_{GK} = 1 kΩ.

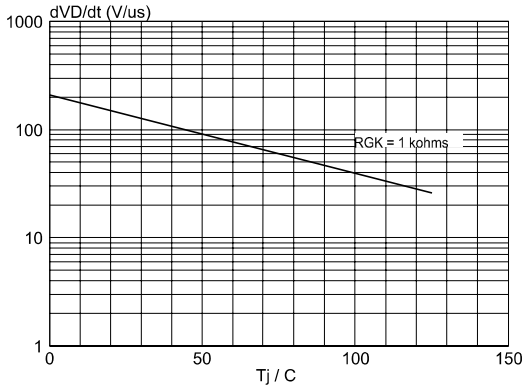


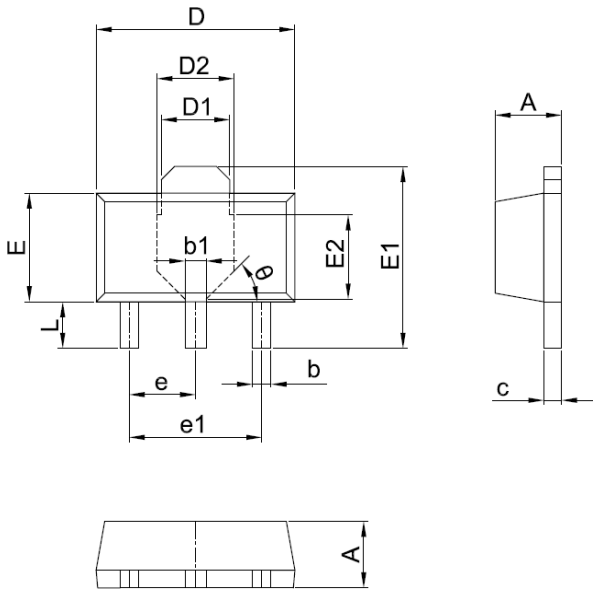
Fig.12. Typical, critical rate of rise of off-state voltage, dV_D/dt versus junction temperature T_j.

Ordering information

Package	Packing Description	Base Quantity	Packing Quantity
SOT-89	Tape/Reel,7"reel	1000pcs/Reel	6000PCS/Box 30000PCS/Carton

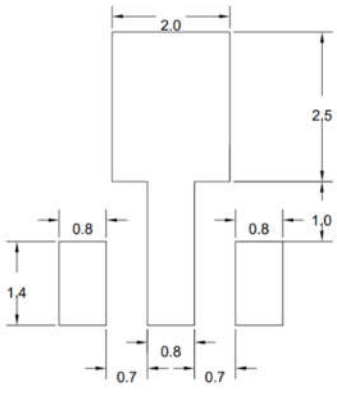
Package Dimensions

SOT-89



Dim	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	1.40	1.60	0.055	0.063
b	0.32	0.52	0.013	0.020
b1	0.38	0.58	0.015	0.023
c	0.35	0.45	0.014	0.018
D	4.40	4.60	0.173	0.181
D1	1.45	1.65	0.057	0.065
D2	1.70	1.80	0.067	0.071
E	2.30	2.60	0.091	0.102
E1	3.95	4.25	0.156	0.167
E2	1.80	2.00	0.071	0.079
e	1.40	1.60	0.055	0.063
e1	2.80	3.20	0.110	0.126
L	0.90	1.20	0.035	0.047

The recommended mounting pad size



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